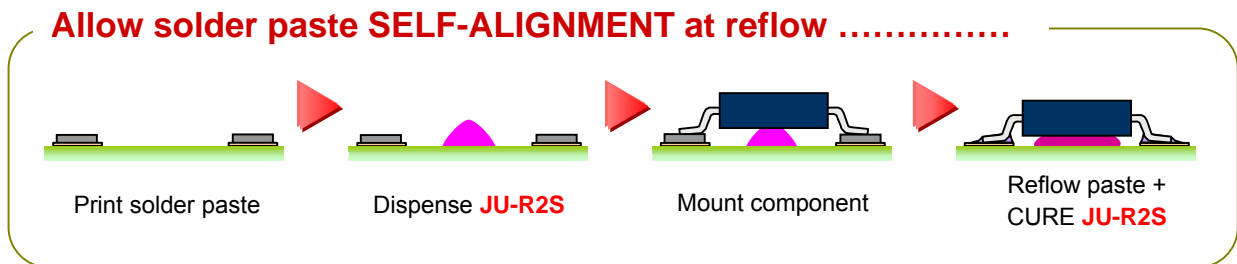


# Lead Free use SMT Adhesive

## JU - R2S



### ■ Features

- 1) Prevent components from **FALLING** down at the 2nd reflow in double-sided reflow.
- 2) Designed to cure at **HIGHER TEMPERATURE** than **MELTING POINT** (218°C; SnAgCu).
- 3) **ALLOW** the SELF-ALIGNMENT EFFECT of lead free solder, ensuring good solderability.

### ■ Specifications

Before curing	Application		Dispense	
	Composition		Epoxy	
	State • Color		Paste • Red	
	Specific gravity		1.22	
	Viscosity (Pa.s • 20°C)		50	
	Thixotropy (20°C)		6.0	
	Non-volatile (105°C • 3 hr)		>99	
	Shelf life	At room temp. (20°C)		3 months
Below 10°C		6 months		
After curing	Bonding strength	2125 square chip	>2 kg	
	Copper plate corrosion (40°C× 95%RH×96hr)		Passed	
	Heat resistivity (250°C × 10sec.)		Passed	
	Surface insulation resistant	Initial value (Ω)		> 1 × 10 <sup>13</sup>
		40°C, 90%RH× 500hr (Ω)		> 1 × 10 <sup>9</sup>
	Water absorption		< 0.5	

## ■ Dispensability

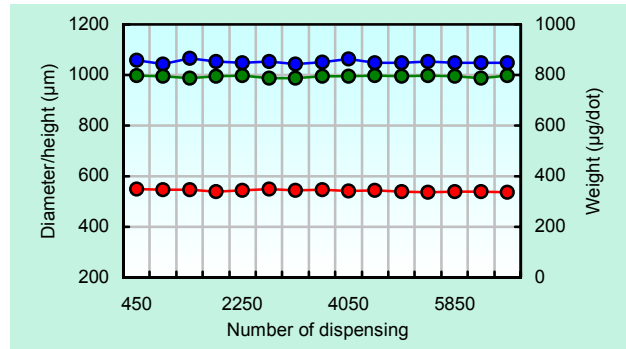
(190 gauge needle, 35°C dispense temperature )



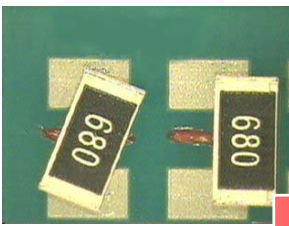
Initial result



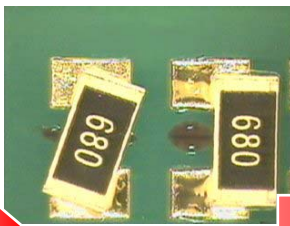
600th dot



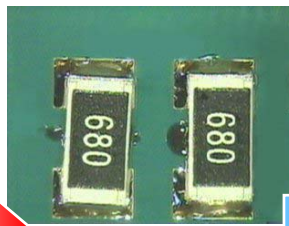
## ■ Self-alignment effect



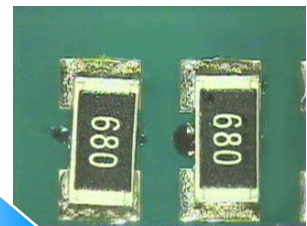
30°C



220°C

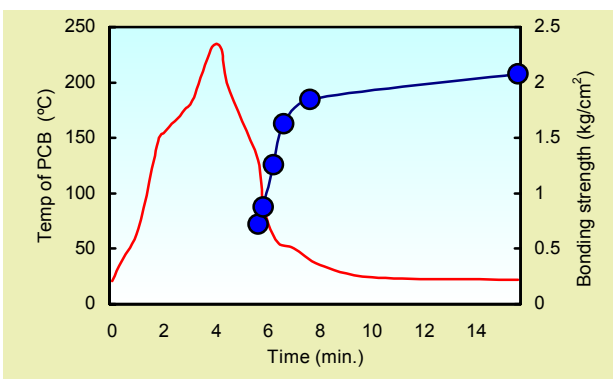


240°C

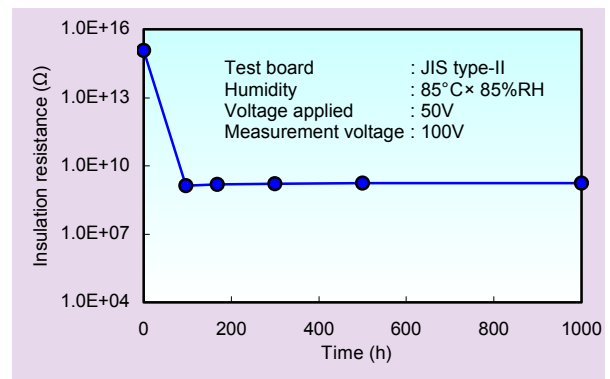


After cooling

## ■ Dependability on bonding strength



## ■ Voltage applied insulation resistance



## ■ Recommended curing temperature

- Pre-heat temp. : 150 ~190°C × >110 sec.
- Over 220°C : 45 sec.
- Peak temp. : 235°C

## ■ Packaging

Available in 300gs tube, 360 cartridge and various types of syringes (5cc, 10cc, 30cc)

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